LOW POWER SCHOTTKY INTEGRATED CIRCUITS

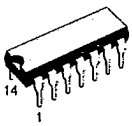
T54LS183
T74LS183

67C 16292 D T-45-07

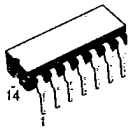
DUAL CARRY-SAVE FULL ADDER

DESCRIPTION

The T54LS183/T74LS183 is a Dual Adder characterising high-speed, high-fan-out Darlington outputs, all inputs are diode clamped for system design simplification. A separate carry output for each bit is designed to be used in multiple intput, carry-save techniques to produce true sum and true carry outputs with two gate delays at least.



B1
Plastic Package



D1/D2
Ceramic Package

M1
Micro Package

C1
Plastic Chip Carrier

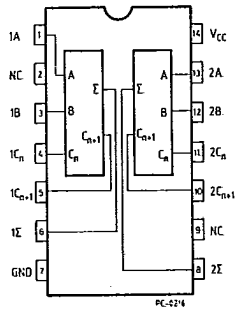
ORDERING NUMBERS:

T54LS183 D2	T74LS183 C1
T74LS183 D1	T74LS183 M1
T74LS183 B1	

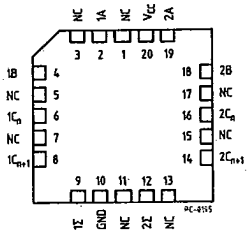
- FOR USE IN HIGH-SPEED WALLACE-TREE SUMMING NETWORKS
- HIGH-SPEED, HIGH-FAN-OUT DARLINGTON OUTPUTS

PIN CONNECTION
(top view)

DUAL IN LINE



CHIP CARRIER



NC = No Internal Connection

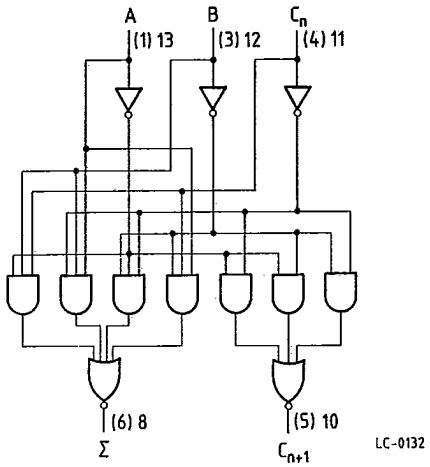
TRUTH TABLE

INPUTS			OUTPUTS	
C_n	B	A	Σ	C_{n+1}
L	L	L	L	L
L	L	H	H	L
L	H	L	H	L
L	H	H	L	H
H	L	L	H	L
H	L	H	L	H
H	H	L	L	H
H	H	H	H	H

H = High level, L = Low level

T54LS183
T74LS183

LOGIC DIAGRAM



V_{CC} = Pin 14
GND = Pin 7
( ) = Pin numbers

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	Supply Voltage	−0.5 to 7	V
V_I	Input Voltage, Applied to Input	−0.5 to 15	V
V_O	Output Voltage, Applied to Output	0 to 10	V
I_I	Input Current, Into Inputs	−30 to 5	mA
I_O	Output Current, Into Outputs	50	mA

Stresses in excess of those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions in excess of those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

GUARANTEED OPERATING RANGES

Part Numbers	Supply Voltage			Temperature
	Min	Typ	Max	
T54LS183D2	4.5 V	5.0 V	5.5 V	−55°C to +125°C
T74LS183XX	4.75 V	5.0 V	5.25 V	0°C to +70°C

XX = package type.

T54LS183
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DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE

Symbol	Parameter		Limits Min.	Limits Typ.	Limits Max.	Test Conditions (Note 1)	Units
V_{IH}	Input HIGH Voltage		2.0			Guaranteed input HIGH Voltage for all Inputs	V
V_{IL}	Input LOW Voltage	54			0.7	Guaranteed input LOW Voltage for all Inputs	V
		74			0.8		
V_{CD}	Input Clamp Diode Voltage			−0.65	−1.5	V_{CC} = MIN, I_{IN} = −18mA	V
V_{OH}	Output HIGH Voltage	54	2.5	3.5		V_{CC} = MIN, I_{OH} = −400μA, V_{IN} = V_{IH} or V_{IL} per Truth Table	V
		74	2.7	3.5			
V_{OL}	Output LOW Voltage	54,74		0.25	0.4	I_{OL} = 4.0mA; V_{CC} = MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table	V
		74		0.35	0.5	I_{OL} = 8.0mA	
I_{IH}	Input HIGH Current				60 0.3	V_{CC} = MAX, V_{IN} = 2.7V V_{CC} = MAX, V_{IN} = 7.0V	μA mA
I_{IL}	Input LOW Current				−1.2	V_{CC} = MAX, V_{IN} = 0.4V	mA
I_{OS}	Output Short Circuit Current (Note 2)		−20		−100	V_{CC} = MAX	mA
I_{CC}	Power Supply Current Total, Output HIGH Total, Output LOW				 14 17	V_{CC} = MAX	mA

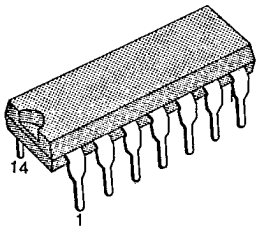
AC CHARACTERISTICS: T_A = 25°C

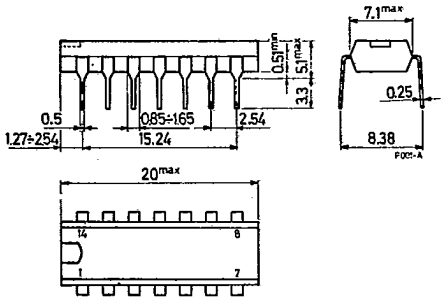
Symbol	Parameter	Limits Min.	Limits Typ.	Limits Max.	Test Conditions	Units
t_{PLH}	Propagation Delay Time Low-to-High Level Output		9.0	15	V_{CC} = 5.0V C_L = 15pF	ns
t_{PHL}	Propagation Delay Time Low-to-High Level Output		12	18		ns

Notes:
1) For conditions shown as MIN or MAX, use the appropriate value specified under guaranteed operating ranges.
2) Not more than one output should be shorted at a time.
3) Typical values are at V_{CC} = 5.0V, T_A = 25°C

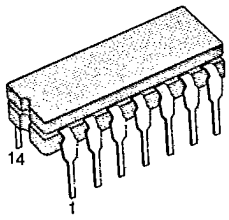
Packages

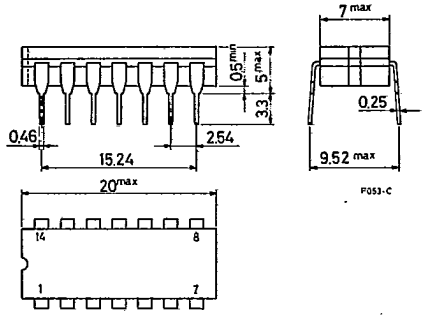
14-LEAD PLASTIC DIP



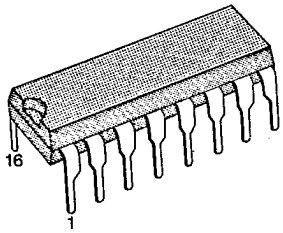


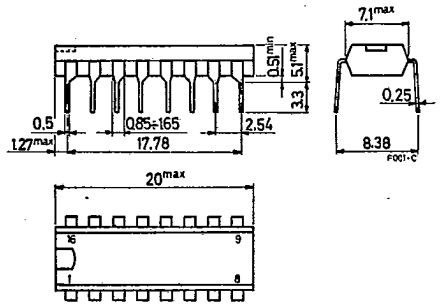
14-LEAD CERAMIC DIP





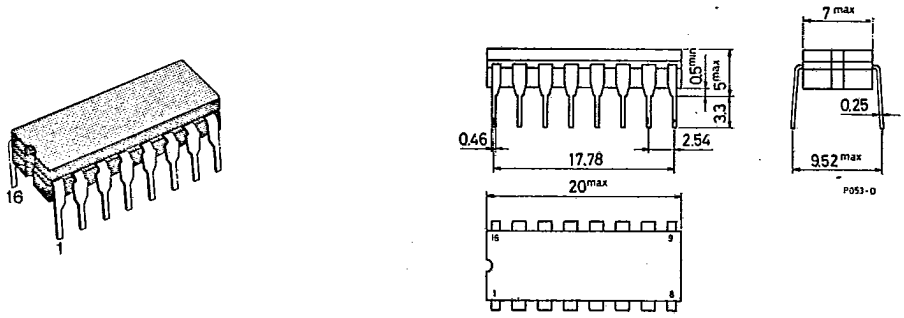
16-LEAD PLASTIC DIP





Packages

16-LEAD CERAMIC DIP



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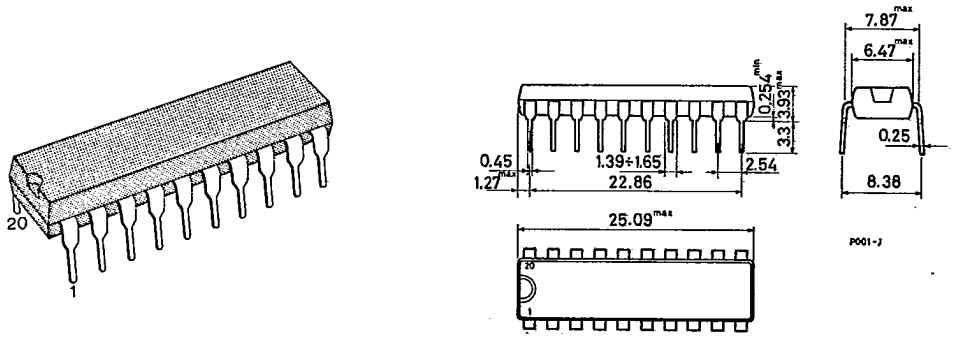

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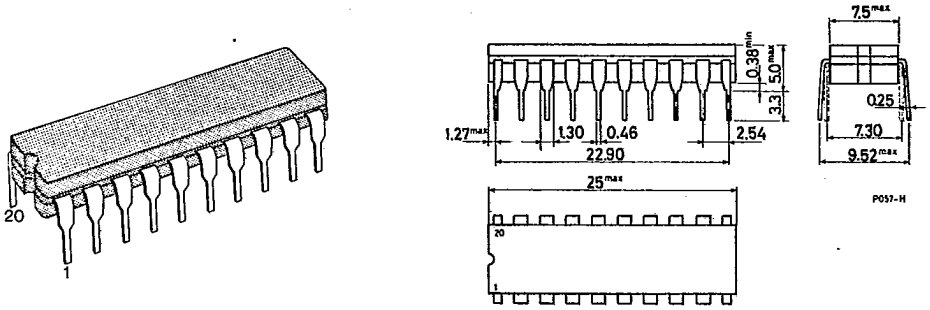
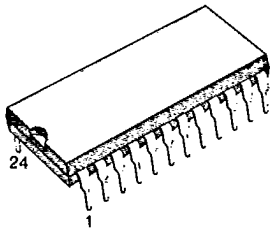
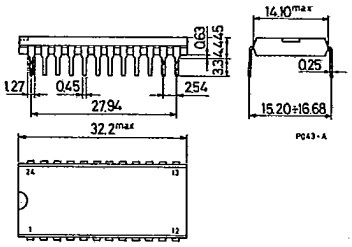


Packages

24-LEAD PLASTIC DIP





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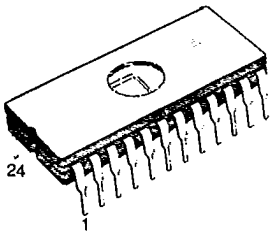
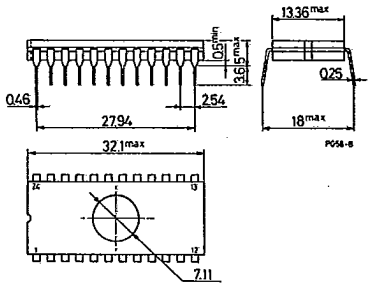
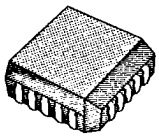
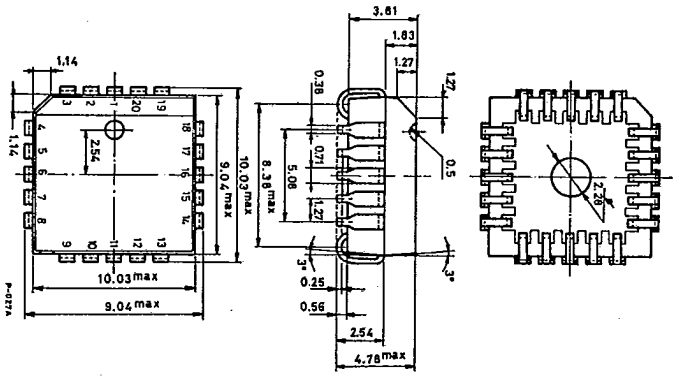




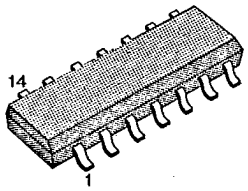
CHIP CARRIER 20 LEAD PLASTIC

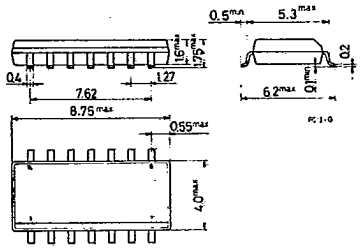




Packages

14-LEAD PLASTIC DIP MICROPACKAGE





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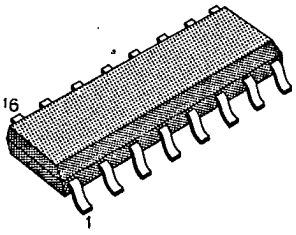

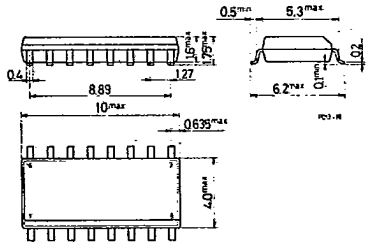

NOTE: FOR 20-LEAD PLASTIC DIP MICROPACKAGE CONTACT SGS

Surface Mounted

One possible solution to the important problem of PWB minimization, is that of using surface mounted components. Integrated circuits in SO (Small Outline) packages are made up of standard chips mounted in very small plastic packages.
The advantages given by using these devices are:

PWB Reduction

This is by far the most important advantage since the reduction of PWB size varies from 40 to 60% in comparison with standard board types. (See page 584 for package dimensions.)

Assembly Cost Reduction

SO Devices require no preliminary operation prior to mounting and can therefore be easily utilized in fully automatic equipment.

Increasing Reliability

The following characteristics lead to a higher level of reliability with respect to their standard packaged counter parts:

- The mounting system is fully automatic
- PWB number and the interconnections between them are reduced when the same number of devices are used.
- The high density of components on the board makes it thermally much more stable.

Noise Reduction and Improved Frequency Response

The reduction of the length of the connecting wires between the leads and the silicon guarantees a more homogeneous propogation delay between the external pins, with respect to the standard type.

Assembly Without Board Holes

The devices are placed on the board and soldered. This technology permits a higher level of tolerance in the positioning (automatic) of the device. For the standard DIP types this must be done with great accuracy due to the insertion of the leads into their holes.